

Full Material Declaration for attached parts list

Report generated: 13 March 2026, 13:57 GMT



Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved on 13 March 2026, 13:54 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.078%	Silicon	7440-21-3	100%
Die attach	Sn-Pb solder	0.033%	Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	10%
			Oxirane, 2,2'-[1,4-butanediylbis(oxyethylene)]bis-	2425-79-8	10%
			Silver	7440-22-4	80%
Encapsulation	EP (Epoxy resin)	60.705%	Carbon black	1333-86-4	1%
			phenolic epoxy resin	61788-97-4	1.5%
			Silicon Dioxide	7631-86-9	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	7.5%
			Quartz sand	60676-86-0	85%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.727%	PALLADIUM, ELEMENTAL	7440-05-3	1%
			COPPER, ELEMENTAL	7440-50-8	99%
Leadfinish	Tin plating	0.693%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	37.764%	Elemental iron	7439-89-6	2.5%
			COPPER, ELEMENTAL	7440-50-8	97.5%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
ESOP-8_(IP)_PB-H-free	Transistor / Regulator	0.077	g
